

SOT142-1

plastic single in-line medium power package; 9 leads

8 February 2016

Package information

1. Package summary

Terminal position code	S (single)
Package type descriptive code	SIL9MP
Package type industry code	SIL9MP
Package style descriptive code	BCC (bottom chip carrier)
Package style suffix code	MP (medium power)
Package body material type	P (plastic)
Mounting method type	T (through-hole mount)
Issue date	12-3-2003

Table 1. Package summary

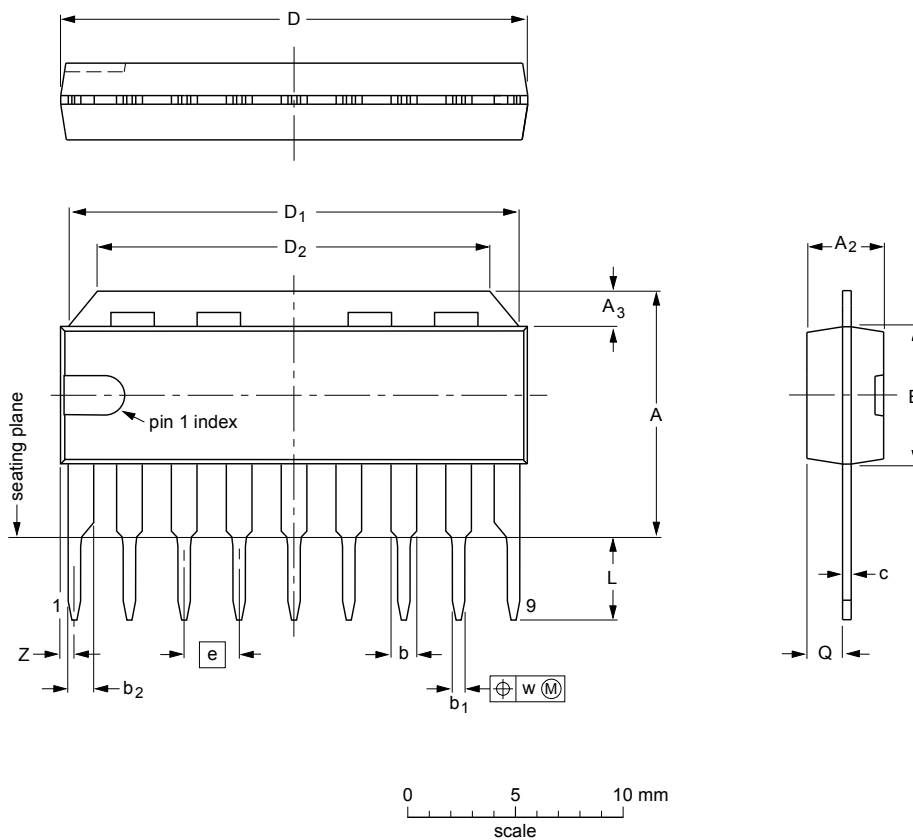
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	21.4	-	21.6	21.8	mm
E	package width	6.2	-	6.35	6.48	mm
A	seated height	11	-	12	12	mm
A ₂	package height	[tbd]	-	3.55	3.7	mm
n ₂	actual quantity of termination	-	-	9	-	



2. Package outline

SIL9MP: plastic single in-line medium power package; 9 leads

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DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₂ max.	A ₃	b	b ₁	b ₂	c	D ⁽¹⁾	D ₁	D ₂	E ⁽¹⁾	e	L	Q	w	Z ⁽¹⁾ max.
mm	12 11	3.7	1.8 1.4	1.40 1.14	0.67 0.50	1.40 1.14	0.48 0.38	21.8 21.4	21.4 20.7	18.6 18.2	6.48 6.20	2.54	3.9 3.4	1.75 1.55	0.25	1

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT142-1					97-12-16 03-03-12

Fig. 1. Package outline SIL9MP (SOT142-1)

3. Legal information

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